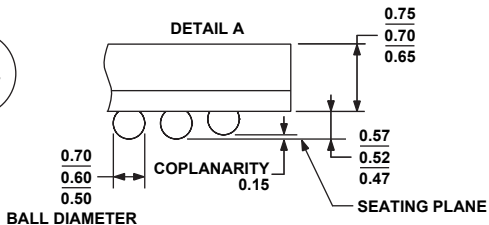
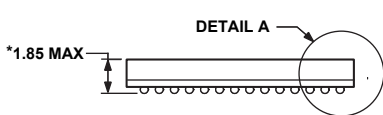
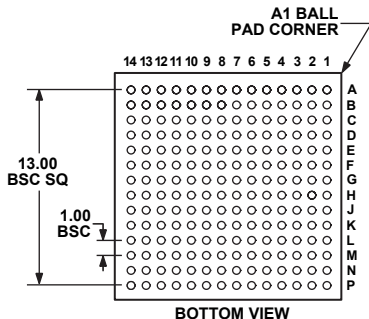
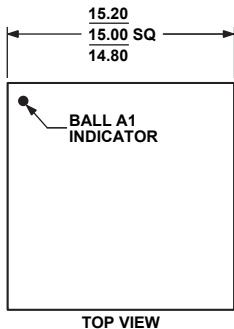


196-Ball Chip Scale Package Ball Grid Array [CSP_BGA]
(BC-196-2)

Dimensions shown in millimeters



*COMPLIANT TO JEDEC STANDARDS MO-192-AAE-1
WITH THE EXCEPTION TO PACKAGE HEIGHT.